

L Number	Hits	Search Text	DB	Time stamp
-	288	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and (etch\$3 plasma) and (nitrogen N2 "n.sub.2") and (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 13:18
-	18	((low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and (etch\$3 plasma) and (nitrogen N2 "n.sub.2") and (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2") ) and etch\$3 same (low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) same ((nitrogen N2 "n.sub.2") with (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/14 16:14
-	71	etch\$3 with (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:10
-	19	etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 19:58
-	9	etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 19:25
-	10	(etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 19:25
-	6	etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:08
-	81	etch\$3 same (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:09
-	2	etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:09
-	36	etch\$3 near (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:11



		USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:54
24	(etch\$3 with (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 near (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2. "O.sub.2" oxygen) near (without free))) ((etch\$3 near (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))))))		

			USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/06 20:54
27	(etch\$3 same (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not ((etch\$3 with (low adj k low-k BCB SiLk) and (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) ((etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) (etch\$3 same (low adj k low-k BCB SiLk) with (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))) not (etch\$3 with (low adj k low-k BCB SiLk) same (oxygen-free oxygen adj free ((O2 "O.sub.2" oxygen) near (without free)))))))			



	12	(low adj k low-k low adj dielectric) and (etch\$3 plasma) and ((nitrogen N2 "N.sub.2") same (C4F8 "C.sub.4 F.sub.8") same ("CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2" CF2H2 CH2F2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/02/17 15:18
	13	(low adj k low-k low adj dielectric) and (etch\$3 plasma) and ((nitrogen N2 "N.sub.2") same (Ar argon))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/02/17 13:55
	23	high adj density with MORI	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/17 15:09
	15	("4512868"   "4609428"   "4859303"   "4971653"   "4985109"   "4985112"   "4990229"   "5024748"   "5091049"   "5114529"   "5122251"   "5242536"   "5336366"   "5385624"   "5449433").PN.		2004/02/17 15:12